



Sheet 1 of 1

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DKT. NO. 501.36127CC2	SERIAL NO. 10/619039
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		APPLICANT KOUBUCHI, et al.	
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Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
CP	AA 5,929,528	7-27-99	Kinugawa	257	776	
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Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation / Abstract	
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CP	AO 8314762	26-11-96	Japan			Corresponding USP '139	
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CP	AU	Lee, et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)", 1996, Symposium on VLSI Technology Digest of Technical Papers, pp. 158-159.
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